## 507051500 12/30/2021

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
MIN-LIN LEE	12/17/2021
SHENG-CHE HUNG	12/17/2021
CHING-SHAN CHANG	12/21/2021
YING-TSUEN LIOU	12/20/2021

#### **RECEIVING PARTY DATA**

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State/Country:	TAIWAN	
Postal Code:	330	
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### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	17564225

#### **CORRESPONDENCE DATA**

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PATENT 507051500 REEL: 058504 FRAME: 0863

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**ATTORNEY DOCKET NUMBER:** 112661-US-PA **NAME OF SUBMITTER:** BELINDA LEE

SIGNATURE: /Belinda Lee/

**DATE SIGNED:** 12/30/2021

**Total Attachments: 2** 

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> PATENT REEL: 058504 FRAME: 0864

# **ASSIGNMENT**

WHEREAS,

1.Min-Lin Lee2.Sheng-Che Hung3.Ching-Shan Chang4.Ying-Tsuen Liou

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: CIRCUIT BOARD AND ELECTRONIC PACKAGE USING THE SAME

[ ] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, 1. First Hi-tec Enterprise Co.,Ltd.

of No.3, Ln. 43, Xingbang Rd., Taoyuan Dist., Taoyuan City 330, Taiwan (R.O.C.)

NEXCOM International Co., Ltd.

of 9F., No.920, Zhongzheng Rd., Zhonghe Dist., New Taipei City 23586, Taiwan (R.O.C.)

 Industrial Technology Research Institute
 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 310401, Taiwan, R. O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assigner further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

PATENT REEL: 058504 FRAME: 0865

# ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Mim - Win Kee	Date:
Sole or First Joint Inventor: Min-Lin Lee	
Signature: <u>Cheng - Che Lung</u> Second Joint Inventor (if any): Sheng-Che Hung	_Date: 707 , 12 , 17
Signature: Shaw Chung Third Joint Inventor (if any): Ching-Shan Chang	
Signature: Ying -TSMen Crow Fourth Joint Inventor (if any): Ying-Tsuen Liou	

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